



## **SPECIFICATION**

• Supplier : Samsung electro-mechanics • Samsung P/N : CL21C330JCANNNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 33pF, 100V, ±5%, C0G, 0805

## A. Samsung Part Number

<u>CL</u> <u>21</u> <u>C</u> <u>330</u> <u>J</u> <u>C</u> <u>A</u> <u>N</u> <u>N</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

1	Series	Samsung Multi-layer Ceramic Capacitor					
2	Size	0805 (inch cod	de) L: 2.0	± 0.1 mm	W:	$1.25 \pm 0.1$	mm
	<b>D</b>	000				NI:	
3	Dielectric	C0G	8	Inner electrode		Ni	
4	Capacitance	<b>33</b> pF		Termination		Cu	
(5)	Capacitance	±5 %		Plating		Sn 100%	(Pb Free)
	tolerance		9	Product		Normal	
6	Rated Voltage	100 V	10	Special		Reserved for	future use
7	Thickness	0.65 ± 0.1	mm ①	Packaging		Cardboard Ty	ype, 7" reel

## B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition				
Capacitance	Within specified tolerance	1Mb±10% 0.5~5Vrms				
Q	1000 min					
Insulation	10,000Mohm or 500Mohm⋅ <i>μ</i> F	Rated Voltage 60~120 sec.				
Resistance	Whichever is Smaller					
Appearance	No abnormal exterior appearance	Microscope (×10)				
Withstanding	No dielectric breakdown or	200% of the rated voltage				
Voltage	mechanical breakdown					
Temperature	COG					
Characterisitcs	(From -55 ℃ to 125 ℃, Capacitance change shoud be within ±30PPM/℃)					
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.				
of Termination	terminal electrode					
Bending Strength	Capacitance change :	Bending to the limit (1mm)				
	within ±5% or ±0.5pF whichever is larger	with 1.0mm/sec.				
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder				
	is to be soldered newly	245±5℃, 3±0.3sec.				
		(preheating : 80~120°C for 10~30sec.)				
Resistance to	Capacitance change :	Solder pot : 270±5℃, 10±1sec.				
Soldering heat	within ±2.5% or ±0.25pF whichever is larger					
	Tan δ, IR : initial spec.					

	Performance	Test condition			
Vibration Test	Capacitance change :	Amplitude : 1.5mm			
	within ±2.5% or ±0.25pF whichever is larger	From 10Hz to 55Hz (return : 1min.)			
	Tan δ, IR : initial spec.	2hours × 3 direction (x, y, z)			
Moisture	Capacitance change :	With rated voltage			
Resistance	within ±7.5% or ±0.75pF whichever is larger	40±2℃, 90~95%RH, 500+12/-0hrs			
	Q: 200 min				
	IR: 500Mohm or 25Mohm $\cdot \mu$ F				
	Whichever is Smaller				
High Temperature	Capacitance change :	With 200% of the rated voltage			
Resistance	within ±3% or ±0.3pF whichever is larger	Max. operating temperature			
	Q: 350 min	1000+48/-0hrs			
	IR : 1000Mohm or 50Mohm $\cdot \mu$ F				
	Whichever is Smaller				
Temperature	Capacitance change :	1 cycle condition			
Cycling	within ±2.5% or ±0.25pF whichever is larger	Min. operating temperatur → 25°C			
	Tan δ, IR : initial spec.	$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}$ C			
		5 cycle test			

## C. Recommended Soldering method :

Reflow ( Reflow Peak Temperature : 260+0/-5  $^{\circ}$ C, 10sec. Max )

<sup>\*</sup> For the more detail Specification, Please refer to the Samsung MLCC catalogue.